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Freescale Semiconductor
Data Sheet

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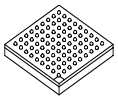
MSC8252



FC-PBGA–783
29 mm × 29 mm

Dual-Core Digital Signal Processor

- Two StarCore SC3850 DSP subsystems, each with an SC3850 DSP core, 32 Kbyte L1 instruction cache, 32 Kbyte L1 data cache, unified 512 Kbyte L2 cache configurable as M2 memory in 64 Kbyte increments, memory management unit (MMU), extended programmable interrupt controller (EPIC), two general-purpose 32-bit timers, debug and profiling support, low-power Wait, Stop, and power-down processing modes, and ECC/EDC support.
- Chip-level arbitration and switching system (CLASS) that provides full fabric non-blocking arbitration between the cores and other initiators and the M2 memory, shared M3 memory, DDR SRAM controllers, device configuration control and status registers, and other targets.
- 1056 Kbyte 128-bit wide M3 memory, 1024 Kbytes of which can be turned off to save power.
- 96 Kbyte boot ROM.
- Three input clocks (one global and two differential).
- Five PLLs (three global and two Serial RapidIO PLLs).
- Two DDR controllers with up to a 400 MHz clock (800 MHz data rate), 64/32 bit data bus, supporting up to a total 2 Gbyte in up to four banks (two per controller) and support for DDR2 and DDR3.
- DMA controller with 32 unidirectional channels supporting 16 memory-to-memory channels with up to 1024 buffer descriptors per channel, and programmable priority, buffer, and multiplexing configuration. It is optimized for DDR SDRAM.
- Up to four independent TDM modules with programmable word size (2, 4, 8, or 16-bit), hardware-base A-law/μ-law conversion, up to 62.5 Mbps data rate for each TDM link, and with glueless interface to E1 or T1 framers that can interface with H-MVIP/H.110 devices, TSI, and codecs such as AC-97.
- High-speed serial interface that supports two Serial RapidIO interfaces, one PCI Express interface, and two SGMII interfaces (multiplexed). The Serial RapidIO interfaces support 1x/4x operation up to 3.125 Gbaud with a single messaging unit and two DMA units. The PCI Express controller supports 32- and 64-bit addressing, x4, x2, and x1 link.
- QUICC Engine technology subsystem with dual RISC processors, 48 Kbyte multi-master RAM, 48 Kbyte instruction RAM, supporting two communication controllers for two Gigabit Ethernet interfaces (RGMII or SGMII), to offload scheduling tasks from the DSP cores, and an SPI.
- I/O Interrupt Concentrator consolidates all chip maskable interrupt and non-maskable interrupt sources and routes then to $\overline{\text{INT_OUT}}$, $\overline{\text{NMI_OUT}}$, and the cores.
- UART that permits full-duplex operation with a bit rate of up to 6.25 Mbps.
- Two general-purpose 32-bit timers for RTOS support per SC3850 core, four timer modules with four 16-bit fully programmable timers, and eight software watchdog timers (SWT).
- Eight programmable hardware semaphores.
- Up to 32 virtual interrupts and a virtual $\overline{\text{NMI}}$ asserted by simple write access.
- I^2C interface.
- Up to 32 GPIO ports, sixteen of which can be configured as external interrupts.
- Boot interface options include Ethernet, Serial RapidIO interface, I^2C, and SPI.
- Supports standard JTAG interface
- Low power CMOS design, with low-power standby and power-down modes, and optimized power-management circuitry.
- 45 nm SOI CMOS technology.

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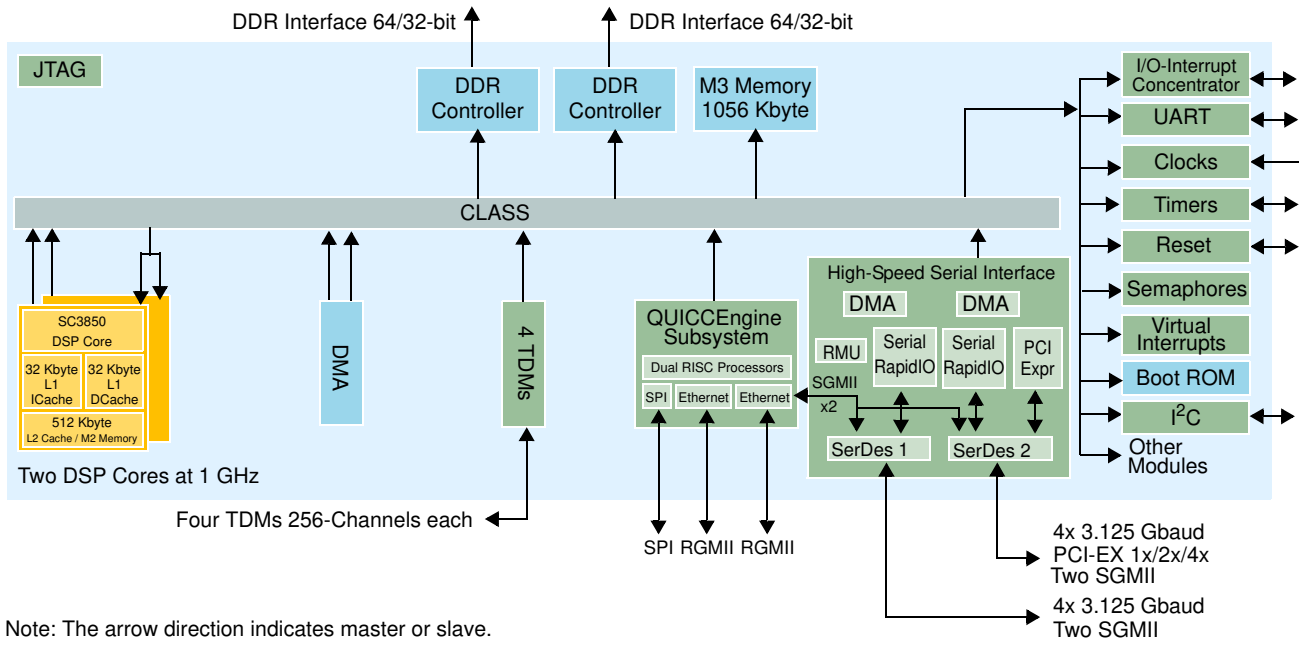

Note: The arrow direction indicates master or slave.

Figure 1. MSC8252 Block Diagram

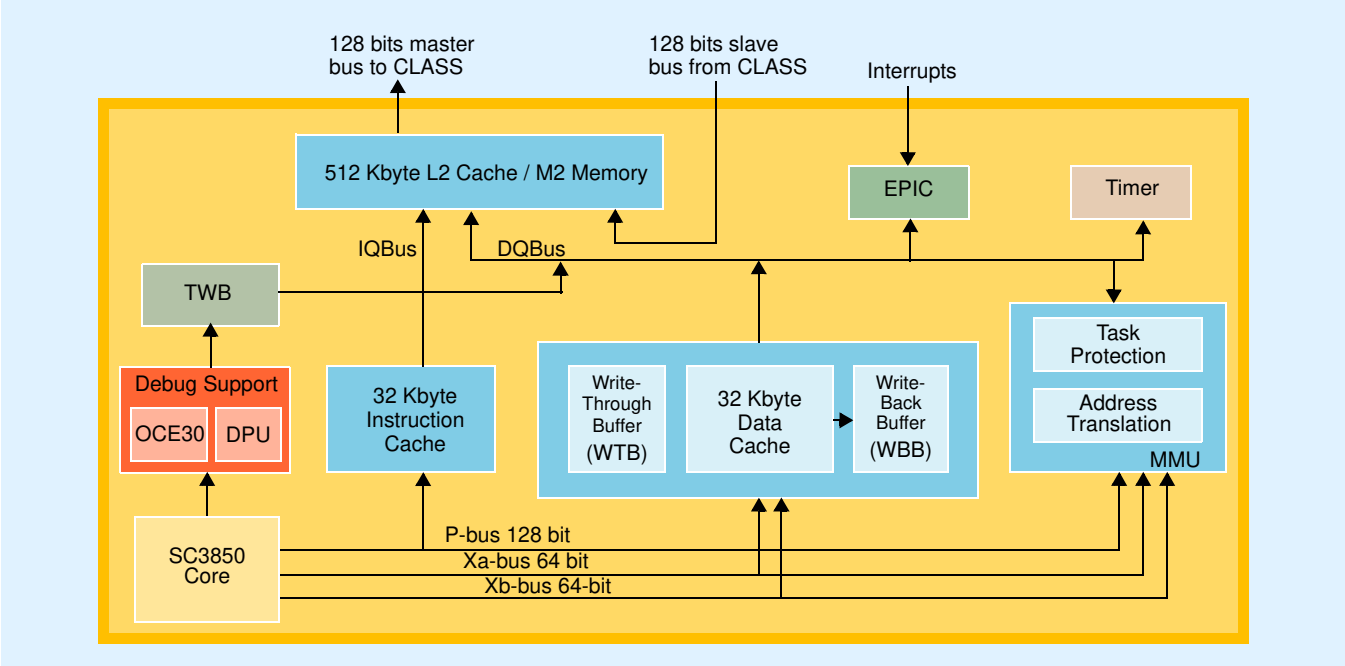

Figure 2. StarCore SC3850 DSP Subsystem Block Diagram

1 Pin Assignment

This section includes diagrams of the MSC8252 package ball grid array layouts and tables showing how the pinouts are allocated for the package.

1.1 FC-PBGA Ball Layout Diagram

The top view of the FC-PBGA package is shown in Figure 3 with the ball location index numbers.

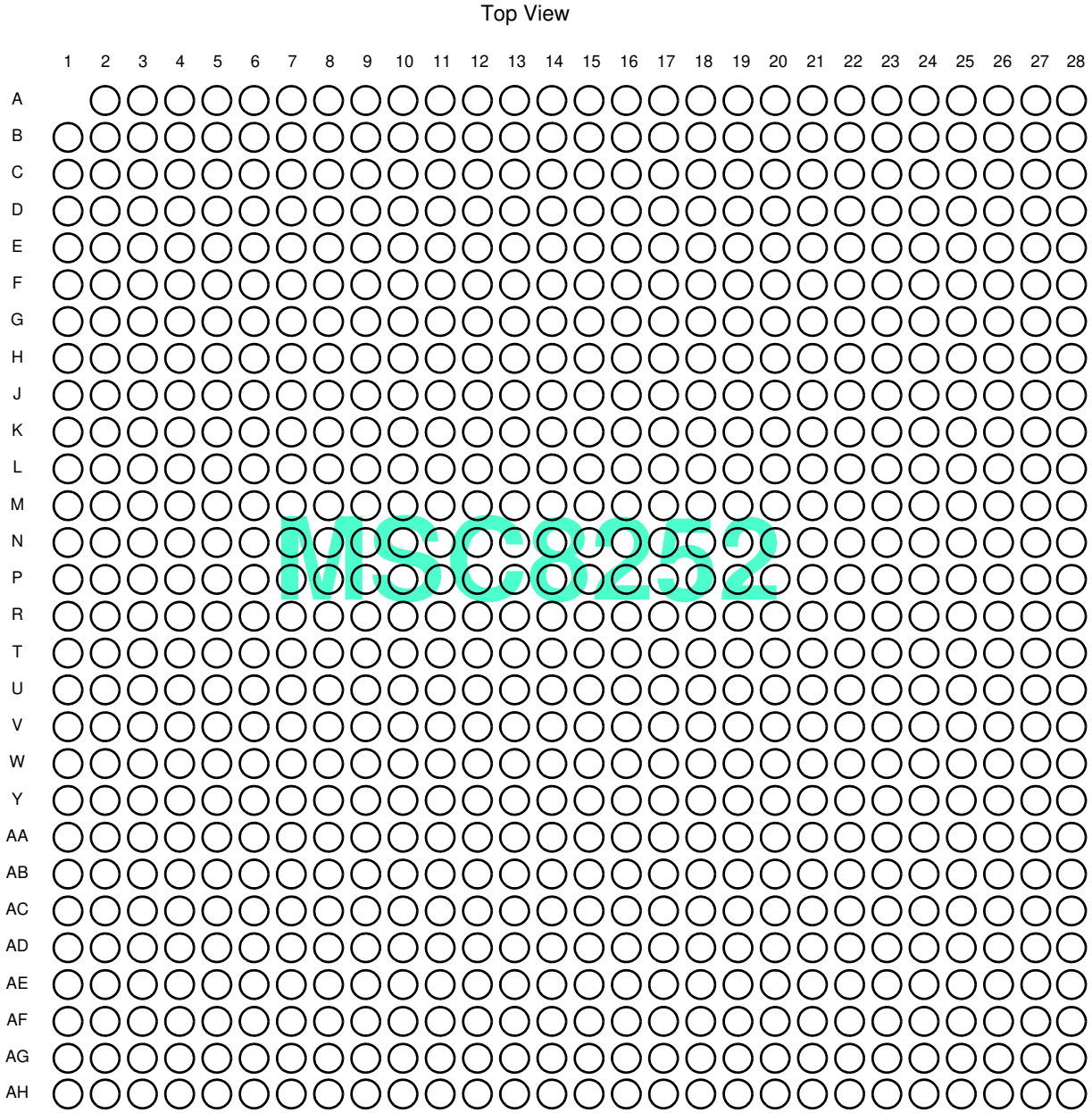

Figure 3. MSC8252 FC-PBGA Package, Top View

1.2 Signal List By Ball Location

Table 1 presents the signal list sorted by ball number. When designing a board, make sure that the power rail for each signal is appropriately considered. The specified power rail must be tied to the voltage level specified in this document if any of the related signal functions are used (active)

Note: The information in Table 1 and Table 2 distinguishes among three concepts. First, the power pins are the balls of the device package used to supply specific power levels for different device subsystems (as opposed to signals). Second, the power rails are the electrical lines on the board that transfer power from the voltage regulators to the device. They are indicated here as the reference power rails for signal lines; therefore, the actual power inputs are listed as N/A with regard to the power rails. Third, symbols used in these tables are the names for the voltage levels (absolute, recommended, and so on) and not the power supplies themselves.

Table 1. Signal List by Ball Number

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
A2	$\overline{\text{M2DQS3}}$	I/O	GVDD2
A3	M2DQS3	I/O	GVDD2
A4	M2ECC0	I/O	GVDD2
A5	$\overline{\text{M2DQS8}}$	I/O	GVDD2
A6	M2DQS8	I/O	GVDD2
A7	M2A5	O	GVDD2
A8	$\overline{\text{M2CK1}}$	O	GVDD2
A9	M2CK1	O	GVDD2
A10	$\overline{\text{M2CS0}}$	O	GVDD2
A11	M2BA0	O	GVDD2
A12	$\overline{\text{M2CAS}}$	O	GVDD2
A13	M2DQ34	I/O	GVDD2
A14	$\overline{\text{M2DQS4}}$	I/O	GVDD2
A15	M2DQS4	I/O	GVDD2
A16	M2DQ50	I/O	GVDD2
A17	$\overline{\text{M2DQS6}}$	I/O	GVDD2
A18	M2DQS6	I/O	GVDD2
A19	M2DQ48	I/O	GVDD2
A20	M2DQ49	I/O	GVDD2
A21	VSS	Ground	N/A
A22	Reserved	NC	—
A23	SXPVDD1	Power	N/A
A24	SXPVSS1	Ground	N/A
A25	Reserved	NC	—
A26	Reserved	NC	—
A27	SXCVDD1	Power	N/A
A28	SXCVSS1	Ground	N/A
B1	M2DQ24	I/O	GVDD2
B2	GVDD2	Power	N/A
B3	M2DQ25	I/O	GVDD2
B4	VSS	Ground	N/A
B5	GVDD2	Power	N/A
B6	M2ECC1	I/O	GVDD2
B7	VSS	Ground	N/A
B8	GVDD2	Power	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
B9	M2A13	O	GVDD2
B10	VSS	Ground	N/A
B11	GVDD2	Power	N/A
B12	$\overline{\text{M2CS1}}$	O	GVDD2
B13	VSS	Ground	N/A
B14	GVDD2	Power	N/A
B15	M2DQ35	I/O	GVDD2
B16	VSS	Ground	N/A
B17	GVDD2	Power	N/A
B18	M2DQ51	I/O	GVDD2
B19	VSS	Ground	N/A
B20	GVDD2	Power	N/A
B21	Reserved	NC	—
B22	Reserved	NC	—
B23	SR1_TXD0	O	SXPVDD1
B24	$\overline{\text{SR1_TXD0}}$	O	SXPVDD1
B25	SXCVDD1	Power	N/A
B26	SXCVSS1	Ground	N/A
B27	$\overline{\text{SR1_RXD0}}$	I	SXCVDD1
B28	SR1_RXD0	I	SXCVDD1
C1	M2DQ28	I/O	GVDD2
C2	M2DM3	O	GVDD2
C3	M2DQ26	I/O	GVDD2
C4	M2ECC4	I/O	GVDD2
C5	M2DM8	O	GVDD2
C6	M2ECC2	I/O	GVDD2
C7	M2CKE1	O	GVDD2
C8	M2CK0	O	GVDD2
C9	$\overline{\text{M2CK0}}$	O	GVDD2
C10	M2BA1	O	GVDD2
C11	M2A1	O	GVDD2
C12	$\overline{\text{M2WE}}$	O	GVDD2
C13	M2DQ37	I/O	GVDD2
C14	M2DM4	O	GVDD2
C15	M2DQ36	I/O	GVDD2
C16	M2DQ32	I/O	GVDD2
C17	M2DQ55	I/O	GVDD2
C18	M2DM6	O	GVDD2
C19	M2DQ53	I/O	GVDD2
C20	M2DQ52	I/O	GVDD2
C21	Reserved	NC	—
C22	SR1_IMP_CAL_RX	I	SXCVDD1
C23	SXPVSS1	Ground	N/A
C24	SXPVDD1	Power	N/A
C25	SR1_REF_CLK	I	SXCVDD1
C26	$\overline{\text{SR1_REF_CLK}}$	I	SXCVDD1

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
C27	Reserved	NC	—
C28	Reserved	NC	—
D1	GVDD2	Power	N/A
D2	VSS	Ground	N/A
D3	M2DQ29	I/O	GVDD2
D4	GVDD2	Power	N/A
D5	VSS	Ground	N/A
D6	M2ECC5	I/O	GVDD2
D7	GVDD2	Power	N/A
D8	VSS	Ground	N/A
D9	M2A8	O	GVDD2
D10	GVDD2	Power	N/A
D11	VSS	Ground	N/A
D12	M2A0	O	GVDD2
D13	GVDD2	Power	N/A
D14	VSS	Ground	N/A
D15	M2DQ39	I/O	GVDD2
D16	GVDD2	Power	N/A
D17	VSS	Ground	N/A
D18	M2DQ54	I/O	GVDD2
D19	GVDD2	Power	N/A
D20	VSS	Ground	N/A
D21	SXPVSS1	Ground	N/A
D22	SXPVDD1	Power	N/A
D23	SR1_TXD1	O	SXPVDD1
D24	$\overline{\text{SR1_TXD1}}$	O	SXPVDD1
D25	SXCVSS1	Ground	N/A
D26	SXCVDD1	Power	N/A
D27	$\overline{\text{SR1_RXD1}}$	I	SXCVDD1
D28	SR1_RXD1	I	SXCVDD1
E1	M2DQ31	I/O	GVDD2
E2	M2DQ30	I/O	GVDD2
E3	M2DQ27	I/O	GVDD2
E4	M2ECC7	I/O	GVDD2
E5	M2ECC6	I/O	GVDD2
E6	M2ECC3	I/O	GVDD2
E7	M2A9	O	GVDD2
E8	M2A6	O	GVDD2
E9	M2A3	O	GVDD2
E10	M2A10	O	GVDD2
E11	$\overline{\text{M2RAS}}$	O	GVDD2
E12	M2A2	O	GVDD2
E13	M2DQ38	I/O	GVDD2
E14	$\overline{\text{M2DQS5}}$	I/O	GVDD2
E15	M2DQS5	I/O	GVDD2
E16	M2DQ33	I/O	GVDD2

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
E17	M2DQ56	I/O	GVDD2
E18	M2DQ57	I/O	GVDD2
E19	$\overline{\text{M2DQS7}}$	I/O	GVDD2
E20	Reserved	NC	—
E21	Reserved	NC	—
E22	Reserved	NC	—
E23	SXPVDD1	Power	N/A
E24	SXPVSS1	Ground	N/A
E25	SR1_PLL_AGND[9]	Ground	SXCVSS1
E26	SR1_PLL_AVDD[9]	Power	SXCVDD1
E27	SXCVSS1	Ground	N/A
E28	SXCVDD1	Power	N/A
F1	VSS	Ground	N/A
F2	GVDD2	Power	N/A
F3	M2DQ16	I/O	GVDD2
F4	VSS	Ground	N/A
F5	GVDD2	Power	N/A
F6	M2DQ17	I/O	GVDD2
F7	VSS	Ground	N/A
F8	GVDD2	Power	N/A
F9	M2BA2	O	GVDD2
F10	VSS	Ground	N/A
F11	GVDD2	Power	N/A
F12	M2A4	O	GVDD2
F13	VSS	Ground	N/A
F14	GVDD2	Power	N/A
F15	M2DQ42	I/O	GVDD2
F16	VSS	Ground	N/A
F17	GVDD2	Power	N/A
F18	M2DQ58	I/O	GVDD2
F19	M2DQS7	I/O	GVDD2
F20	GVDD2	Power	N/A
F21	SXPVDD1	Power	N/A
F22	SXPVSS1	Ground	N/A
F23	SR1_TXD2/SG1_TX[4]	O	SXPVDD1
F24	$\overline{\text{SR1_TXD2}}$/$\overline{\text{SG1_TX}}$[4]	O	SXPVDD1
F25	SXCVDD1	Power	N/A
F26	SXCVSS1	Ground	N/A
F27	$\overline{\text{SR1_RXD2}}$/$\overline{\text{SG1_RX}}$[4]	I	SXCVDD1
F28	SR1_RXD2/SG1_RX[4]	I	SXCVDD1
G1	$\overline{\text{M2DQS2}}$	I/O	GVDD2
G2	M2DQS2	I/O	GVDD2
G3	M2DQ19	I/O	GVDD2
G4	M2DM2	O	GVDD2
G5	M2DQ21	I/O	GVDD2
G6	M2DQ22	I/O	GVDD2

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
G7	M2CKE0	O	GVDD2
G8	M2A11	O	GVDD2
G9	M2A7	O	GVDD2
G10	$\overline{\text{M2CK2}}$	O	GVDD2
G11	M2APAR_OUT	O	GVDD2
G12	M2ODT1	O	GVDD2
G13	$\overline{\text{M2APAR_IN}}$	I	GVDD2
G14	M2DQ43	I/O	GVDD2
G15	M2DM5	O	GVDD2
G16	M2DQ44	I/O	GVDD2
G17	M2DQ40	I/O	GVDD2
G18	M2DQ59	I/O	GVDD2
G19	M2DM7	O	GVDD2
G20	M2DQ60	I/O	GVDD2
G21	Reserved	NC	—
G22	Reserved	NC	—
G23	SXPVSS1	Ground	N/A
G24	SXPVDD1	Power	N/A
G25	SR1_IMP_CAL_TX	I	SXCVDD1
G26	SXCVSS1	Ground	N/A
G27	Reserved	NC	—
G28	Reserved	NC	—
H1	GVDD2	Power	N/A
H2	VSS	Ground	N/A
H3	M2DQ18	I/O	GVDD2
H4	GVDD2	Power	N/A
H5	VSS	Ground	N/A
H6	M2DQ20	I/O	GVDD2
H7	GVDD2	Power	N/A
H8	VSS	Ground	N/A
H9	M2A15	O	GVDD2
H10	M2CK2	O	GVDD2
H11	M2MDIC0	I/O	GVDD2
H12	M2VREF	I	GVDD2
H13	M2MDIC1	I/O	GVDD2
H14	M2DQ46	I/O	GVDD2
H15	M2DQ47	I/O	GVDD2
H16	M2DQ45	I/O	GVDD2
H17	M2DQ41	I/O	GVDD2
H18	M2DQ62	I/O	GVDD2
H19	M2DQ63	I/O	GVDD2
H20	M2DQ61	I/O	GVDD2
H21	Reserved	NC	—
H22	Reserved	NC	—
H23	SR1_TXD3/SG2_TX[4]	O	SXPVDD1
H24	$\overline{\text{SR1_TXD3}}$/SG2_TX[4]	O	SXPVDD1

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
H25	SXCVSS1	Ground	N/A
H26	SXCVDD1	Power	N/A
H27	$\overline{\text{SR1_RXD3}}$/$\overline{\text{SG2_RX}}$[4]	I	SXCVDD1
H28	SR1_RXD3/SG2_RX[4]	I	SXCVDD1
J1	M2DQS1	I/O	GVDD2
J2	$\overline{\text{M2DQS1}}$	I/O	GVDD2
J3	M2DQ10	I/O	GVDD2
J4	M2DQ11	I/O	GVDD2
J5	M2DQ14	I/O	GVDD2
J6	M2DQ23	I/O	GVDD2
J7	M2ODT0	O	GVDD2
J8	M2A12	O	GVDD2
J9	M2A14	O	GVDD2
J10	VSS	Ground	N/A
J11	GVDD2	Power	N/A
J12	VSS	Ground	N/A
J13	GVDD2	Power	N/A
J14	VSS	Ground	N/A
J15	GVDD2	Power	N/A
J16	VSS	Ground	N/A
J17	GVDD2	Power	N/A
J18	VSS	Ground	N/A
J19	GVDD2	Power	N/A
J20	Reserved	NC	—
J21	Reserved	NC	—
J22	Reserved	NC	—
J23	SXPVDD1	Power	N/A
J24	SXPVSS1	Ground	N/A
J25	SXCVDD1	Power	N/A
J26	SXCVSS1	Ground	N/A
J27	SXCVDD1	Power	N/A
J28	SXCVSS1	Ground	N/A
K1	VSS	Ground	N/A
K2	GVDD2	Power	N/A
K3	M2DM1	O	GVDD2
K4	VSS	Ground	N/A
K5	GVDD2	Power	N/A
K6	M2DQ0	I/O	GVDD2
K7	VSS	Ground	N/A
K8	GVDD2	Power	N/A
K9	M2DQ5	I/O	GVDD2
K10	VSS	Ground	N/A
K11	VDD	Power	N/A
K12	VSS	Ground	N/A
K13	VDD	Power	N/A
K14	VSS	Ground	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
K15	VDD	Power	N/A
K16	VSS	Ground	N/A
K17	VSS	Ground	N/A
K18	VSS	Ground	N/A
K19	VDD	Power	N/A
K20	Reserved	NC	—
K21	Reserved	NC	—
K22	Reserved	NC	—
K23	SXPVDD2	Power	N/A
K24	SXPVSS2	Ground	N/A
K25	SXCVDD2	Power	N/A
K26	SXCVSS2	Ground	N/A
K27	SXCVDD2	Power	N/A
K28	SXCVSS2	Ground	N/A
L1	M2DQ9	I/O	GVDD2
L2	M2DQ12	I/O	GVDD2
L3	M2DQ13	I/O	GVDD2
L4	$\overline{\text{M2DQS0}}$	I/O	GVDD2
L5	M2DQS0	I/O	GVDD2
L6	M2DM0	O	GVDD2
L7	M2DQ3	I/O	GVDD2
L8	M2DQ2	I/O	GVDD2
L9	M2DQ4	I/O	GVDD2
L10	VDD	Power	N/A
L11	VSS	Ground	N/A
L12	M3VDD	Power	N/A
L13	VSS	Ground	N/A
L14	VSS	Ground	N/A
L15	VSS	Ground	N/A
L16	VSS	Ground	N/A
L17	VSS	Ground	N/A
L18	VDD	Power	N/A
L19	VSS	Ground	N/A
L20	Reserved	NC	—
L21	Reserved	NC	—
L22	Reserved	NC	—
L23	SR2_TXD3/PE_TXD3/SG2_TX[4]	O	SXPVDD2
L24	$\overline{\text{SR2_TXD3}}$/$\overline{\text{PE_TXD3}}$/$\overline{\text{SG2_TX}}$[4]	O	SXPVDD2
L25	SXCVSS2	Ground	N/A
L26	SXCVDD2	Power	N/A
L27	$\overline{\text{SR2_RXD3}}$/$\overline{\text{PE_RXD3}}$/$\overline{\text{SG2_RX}}$[4]	I	SXCVDD2
L28	SR2_RXD3/PE_RXD3/SG2_RX[4]	I	SXCVDD2
M1	M2DQ8	I/O	GVDD2
M2	VSS	Ground	N/A
M3	GVDD2	Power	N/A
M4	M2DQ15	I/O	GVDD2

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
M5	M2DQ1	I/O	GVDD2
M6	VSS	Ground	N/.A
M7	GVDD2	Power	N/A
M8	M2DQ7	I/O	GVDD2
M9	M2DQ6	I/O	GVDD2
M10	VSS	Ground	N/A
M11	VDD	Power	N/A
M12	VSS	Ground	N/A
M13	VDD	Power	N/A
M14	VSS	Ground	N/A
M15	VSS	Ground	N/A
M16	VSS	Ground	N/A
M17	VSS	Ground	N/A
M18	VSS	Ground	N/A
M19	VDD	Power	N/A
M20	Reserved	NC	—
M21	Reserved	NC	—
M22	Reserved	NC	—
M23	SXPVSS2	Ground	N/A
M24	SXPVDD2	Power	N/A
M25	SR2_IMP_CAL_TX	I	SXCVDD2
M26	SXCVSS2	Ground	N/A
M27	Reserved	NC	—
M28	Reserved	NC	—
N1	VSS	Ground	N/A
N2	$\overline{\text{TRST}}$[7]	I	QVDD
N3	$\overline{\text{PORESET}}$[7]	I	QVDD
N4	VSS	Ground	N/A
N5	TMS[7]	I	QVDD
N6	CLKOUT	O	QVDD
N7	VSS	Ground	N/A
N8	VSS	Ground	N/A
N9	VSS	Ground	N/A
N10	VDD	Power	N/A
N11	VSS	Ground	N/A
N12	M3VDD	Power	N/A
N13	VSS	Ground	N/A
N14	VSS	Ground	N/A
N15	VSS	Ground	N/A
N16	VDD	Power	N/A
N17	VSS	Ground	N/A
N18	VDD	Power	N/A
N19	VSS	Ground	N/A
N20	Reserved	NC	—
N21	SXPVDD2	Power	N/A
N22	SXPVSS2	Ground	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
N23	SR2_TXD2/PE_TXD2/SG1_TX[4]	O	SXPVDD2
N24	$\overline{\text{SR2_TXD2}}$/$\overline{\text{PE_TXD2}}$/$\overline{\text{SG1_TX}}$[4]	O	SXPVDD2
N25	SXCVDD2	Power	N/A
N26	SXCVSS2	Ground	N/A
N27	$\overline{\text{SR2_RXD2}}$/$\overline{\text{PE_RXD2}}$/$\overline{\text{SG1_RX}}$[4]	I	SXCVDD2
N28	SR2_RXD2/PE_RXD2/SG1_RX[4]	I	SXCVDD2
P1	CLKIN	I	QVDD
P2	EE0	I	QVDD
P3	QVDD	Power	N/A
P4	VSS	Ground	N/A
P5	STOP_BS	I	QVDD
P6	QVDD	Power	N/A
P7	VSS	Ground	N/A
P8	PLL0_AVDD[9]	Power	VDD
P9	PLL2_AVDD[9]	Power	VDD
P10	VSS	Ground	N/A
P11	VDD	Power	N/A
P12	VSS	Ground	N/A
P13	VDD	Power	N/A
P14	VSS	Ground	N/A
P15	VSS	Ground	N/A
P16	VSS	Ground	N/A
P17	VSS	Ground	N/A
P18	VSS	Ground	N/A
P19	VDD	Power	N/A
P20	Reserved	NC	—
P21	Reserved	NC	—
P22	Reserved	NC	—
P23	SXPVDD2	Power	N/A
P24	SXPVSS2	Ground	N/A
P25	SR2_PLL_AGND[9]	Ground	SXCVSS2
P26	SR2_PLL_AVDD[9]	Power	SXCVDD2
P27	SXCVSS2	Ground	N/A
P28	SXCVDD2	Power	N/A
R1	VSS	Ground	N/A
R2	$\overline{\text{NMI}}$	I	QVDD
R3	$\overline{\text{NMI_OUT}}$[6]	O	QVDD
R4	$\overline{\text{HRESET}}$[6,7]	I/O	QVDD
R5	$\overline{\text{INT_OUT}}$[6]	O	QVDD
R6	EE1	O	QVDD
R7	VSS	Ground	N/A
R8	PLL1_AVDD[9]	Power	VDD
R9	VSS	Ground	N/A
R10	VDD	Power	N/A
R11	VSS	Non-user	N/A
R12	VDD	Power	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
R13	VSS	Ground	N/A
R14	VDD	Power	N/A
R15	VSS	Ground	N/A
R16	VSS	Ground	N/A
R17	VSS	Ground	N/A
R18	VDD	Power	N/A
R19	VSS	Ground	N/A
R20	VSS	Non-user	N/A
R21	SXPVSS2	Ground	N/A
R22	SXPVDD2	Power	N/A
R23	SR2_TXD1/PE_TXD1[4]	O	SXPVDD2
R24	$\overline{\text{SR2_TXD1}}$/$\overline{\text{PE_TXD1}}$[4]	O	SXPVDD2
R25	SXCVSS2	Ground	N/A
R26	SXCVDD2	Power	N/A
R27	$\overline{\text{SR2_RXD1}}$/$\overline{\text{PE_RXD1}}$[4]	I	SXCVDD2
R28	SR2_RXD1/PE_RXD1[4]	I	SXCVDD2
T1	VSS	Ground	N/A
T2	TCK	I	QVDD
T3	$\overline{\text{SRESET}}$[6,7]	I/O	QVDD
T4	TDI	I	QVDD
T5	VSS	Ground	N/A
T6	TDO	O	QVDD
T7	VSS	Ground	N/A
T8	VSS	Ground	N/A
T9	QVDD	Power	N/A
T10	VSS	Ground	N/A
T11	VDD	Power	N/A
T12	VSS	Ground	N/A
T13	M3VDD	Power	N/A
T14	VSS	Ground	N/A
T15	VDD	Power	N/A
T16	VSS	Ground	N/A
T17	VSS	Ground	N/A
T18	VSS	Ground	N/A
T19	VDD	Power	N/A
T20	VSS	Ground	N/A
T21	VSS	Non-user	N/A
T22	SR2_IMP_CAL_RX	I	SXCVDD2
T23	SXPVSS2	Ground	N/A
T24	SXPVDD2	Power	N/A
T25	SR2_REF_CLK	I	SXCVDD2
T26	$\overline{\text{SR2_REF_CLK}}$	I	SXCVDD2
T27	Reserved	NC	—
T28	Reserved	NC	—
U1	M1DQ8	I/O	GVDD1
U2	VSS	Ground	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
U3	GVDD1	Power	N/A
U4	M1DQ15	I/O	GVDD1
U5	M1DQ1	I/O	GVDD1
U6	VSS	Ground	N/A
U7	GVDD1	Power	N/A
U8	M1DQ7	I/O	GVDD1
U9	M1DQ6	I/O	GVDD1
U10	VDD	Power	N/A
U11	VSS	Ground	N/A
U12	M3VDD	Power	N/A
U13	VSS	Ground	N/A
U14	VDD	Power	N/A
U15	VSS	Ground	N/A
U16	VDD	Power	N/A
U17	VSS	Ground	N/A
U18	VDD	Power	N/A
U19	VSS	Ground	N/A
U20	VSS	Ground	N/A
U21	VSS	Ground	N/A
U22	VSS	Non-user	N/A
U23	SR2_TXD0/PE_TXD0[4]	O	SXPVDD2
U24	$\overline{\text{SR2_TXD0}}$/$\overline{\text{PE_TXD0}}$[4]	O	SXPVDD2
U25	SXCVDD2	Power	N/A
U26	SXCVSS2	Ground	N/A
U27	$\overline{\text{SR2_RXD0}}$/$\overline{\text{PE_RXD0}}$[4]	I	SXCVDD2
U28	SR2_RXD0/PE_RXD0[4]	I	SXCVDD2
V1	M1DQ9	I/O	GVDD1
V2	M1DQ12	I/O	GVDD1
V3	M1DQ13	I/O	GVDD1
V4	$\overline{\text{M1DQS0}}$	I/O	GVDD1
V5	M1DQS0	I/O	GVDD1
V6	M1DM0	O	GVDD1
V7	M1DQ3	I/O	GVDD1
V8	M1DQ2	I/O	GVDD1
V9	M1DQ4	I/O	GVDD1
V10	VSS	Ground	N/A
V11	VDD	Power	N/A
V12	VSS	Ground	N/A
V13	VDD	Power	N/A
V14	VSS	Ground	N/A
V15	VDD	Power	N/A
V16	VSS	Ground	N/A
V17	VDD	Power	N/A
V18	VSS	Ground	N/A
V19	VDD	Power	N/A
V20	NVDD	Power	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
V21	RCW_LSEL_3/RC20	I/O	NVDD
V22	RCW_LSEL_2/RC19	I/O	NVDD
V23	SXPVDD2	Power	N/A
V24	SXPVSS2	Ground	N/A
V25	RCW_LSEL_1/RC18	I/O	NVDD
V26	RC21	I	NVDD
V27	SXCVDD2	Power	N/A
V28	SXCVSS2	Ground	N/A
W1	VSS	Ground	N/A
W2	GVDD1	Power	N/A
W3	M1DM1	O	GVDD1
W4	VSS	Ground	N/A
W5	GVDD1	Power	N/A
W6	M1DQ0	I/O	GVDD1
W7	VSS	Ground	N/A
W8	GVDD1	Power	N/A
W9	M1DQ5	I/O	GVDD1
W10	VDD	Power	N/A
W11	VSS	Ground	N/A
W12	VDD	Power	N/A
W13	VSS	Ground	N/A
W14	VDD	Power	N/A
W15	VSS	Ground	N/A
W16	VDD	Power	N/A
W17	VSS	Ground	N/A
W18	VDD	Power	N/A
W19	VSS	Ground	N/A
W20	VSS	Ground	N/A
W21	RCW_LSEL0/RC17	I/O	NVDD
W22	GPIO19/SPI_MISO[5,8]	I/O	NVDD
W23	VSS	Ground	N/A
W24	NVDD	Power	N/A
W25	GPIO11/IRQ11/RC11[5,8]	I/O	NVDD
W26	GPIO3/DRQ1/IRQ3/RC3[5,8]	I/O	NVDD
W27	GPIO7/IRQ7/RC7[5,8]	I/O	NVDD
W28	GPIO2/IRQ2/RC2[5,8]	I/O	NVDD
Y1	M1DQS1	I/O	GVDD1
Y2	M1DQS1	I/O	GVDD1
Y3	M1DQ10	I/O	GVDD1
Y4	M1DQ11	I/O	GVDD1
Y5	M1DQ14	I/O	GVDD1
Y6	M1DQ23	I/O	GVDD1
Y7	M1ODT0	O	GVDD1
Y8	M1A12	O	GVDD1
Y9	M1A14	O	GVDD1
Y10	VSS	Ground	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
Y11	GVDD1	Power	N/A
Y12	VSS	Ground	N/A
Y13	GVDD1	Power	N/A
Y14	VSS	Ground	N/A
Y15	GVDD1	Power	N/A
Y16	VSS	Ground	N/A
Y17	GVDD1	Power	N/A
Y18	VSS	Ground	N/A
Y19	GVDD1	Power	N/A
Y20	VSS	Ground	N/A
Y21	NVDD	Power	N/A
Y22	GPIO20/$\overline{\text{SPI_SL}}$[5,8]	I/O	NVDD
Y23	GPIO17/SPI_SCK[5,8]	I/O	NVDD
Y24	GPIO14/DRQ0/$\overline{\text{IRQ14}}$/RC14[5,8]	I/O	NVDD
Y25	GPIO12/$\overline{\text{IRQ12}}$/RC12[5,8]	I/O	NVDD
Y26	GPIO8/$\overline{\text{IRQ8}}$/RC8[5,8]	I/O	NVDD
Y27	NVDD	Power	N/A
Y28	VSS	Ground	N/A
AA1	GVDD1	Power	N/A
AA2	VSS	Ground	N/A
AA3	M1DQ18	I/O	GVDD1
AA4	GVDD1	Power	N/A
AA5	VSS	Ground	N/A
AA6	M1DQ20	I/O	GVDD1
AA7	GVDD1	Power	N/A
AA8	VSS	Ground	N/A
AA9	M1A15	O	GVDD1
AA10	M1CK2	O	GVDD1
AA11	M1MDIC0	I/O	GVDD1
AA12	M1VREF	I	GVDD1
AA13	M1MDIC1	I/O	GVDD1
AA14	M1DQ46	I/O	GVDD1
AA15	M1DQ47	I/O	GVDD1
AA16	M1DQ45	I/O	GVDD1
AA17	M1DQ41	I/O	GVDD1
AA18	M1DQ62	I/O	GVDD1
AA19	M1DQ63	I/O	GVDD1
AA20	M1DQ61	I/O	GVDD1
AA21	VSS	Ground	N/A
AA22	GPIO21[5,8]	I/O	NVDD
AA23	GPIO18/SPI_MOSI[5,8]	I/O	NVDD
AA24	GPIO16/RC16[5,8]	I/O	NVDD
AA25	GPIO4/DDN1/$\overline{\text{IRQ4}}$/RC4[5,8]	I/O	NVDD
AA26	GPIO9/$\overline{\text{IRQ9}}$/RC9[5,8]	I/O	NVDD
AA27	GPIO6/$\overline{\text{IRQ6}}$/RC6[5,8]	I/O	NVDD
AA28	GPIO1/$\overline{\text{IRQ1}}$/RC1[5,8]	I/O	NVDD

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
AB1	$\overline{\text{M1DQS2}}$	I/O	GVDD1
AB2	M1DQS2	I/O	GVDD1
AB3	M1DQ19	I/O	GVDD1
AB4	M1DM2	O	GVDD1
AB5	M1DQ21	I/O	GVDD1
AB6	M1DQ22	I/O	GVDD1
AB7	M1CKE0	O	GVDD1
AB8	M1A11	O	GVDD1
AB9	M1A7	O	GVDD1
AB10	$\overline{\text{M1CK2}}$	O	GVDD1
AB11	M1APAR_OUT	O	GVDD1
AB12	M1ODT1	O	GVDD1
AB13	$\overline{\text{M1APAR_IN}}$	I	GVDD1
AB14	M1DQ43	I/O	GVDD1
AB15	M1DM5	O	GVDD1
AB16	M1DQ44	I/O	GVDD1
AB17	M1DQ40	I/O	GVDD1
AB18	M1DQ59	I/O	GVDD1
AB19	M1DM7	O	GVDD1
AB20	M1DQ60	I/O	GVDD1
AB21	VSS	Ground	N/A
AB22	GPIO31/I2C_SDA[5,8]	I/O	NVDD
AB23	GPIO27/TMR4/RCW_SRC0[5,8]	I/O	NVDD
AB24	GPIO25/TMR2/RCW_SRC1[5,8]	I/O	NVDD
AB25	GPIO24/TMR1/RCW_SRC2[5,8]	I/O	NVDD
AB26	GPIO10/$\overline{\text{IRQ10}}$/RC10[5,8]	I/O	NVDD
AB27	GPIO5/$\overline{\text{IRQ5}}$/RC5[5,8]	I/O	NVDD
AB28	GPIO0/$\overline{\text{IRQ0}}$/RC0[5,8]	I/O	NVDD
AC1	VSS	Ground	N/A
AC2	GVDD1	Power	N/A
AC3	M1DQ16	I/O	GVDD1
AC4	VSS	Ground	N/A
AC5	GVDD1	Power	N/A
AC6	M1DQ17	I/O	GVDD1
AC7	VSS	Ground	N/A
AC8	GVDD1	Power	N/A
AC9	M1BA2	O	GVDD1
AC10	VSS	Ground	N/A
AC11	GVDD1	Power	N/A
AC12	M1A4	O	GVDD1
AC13	VSS	Ground	N/A
AC14	GVDD1	Power	N/A
AC15	M1DQ42	I/O	GVDD1
AC16	VSS	Ground	N/A
AC17	GVDD1	Power	N/A
AC18	M1DQ58	I/O	GVDD1

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
AC19	VSS	Ground	N/A
AC20	GVDD1	Power	N/A
AC21	VSS	Ground	N/A
AC22	NVDD	Power	N/A
AC23	GPIO30/I2C_SCL[5,8]	I/O	NVDD
AC24	GPIO26/TMR3[5,8]	I/O	NVDD
AC25	VSS	Ground	N/A
AC26	NVDD	Power	N/A
AC27	GPIO23/TMR0[5,8]	I/O	NVDD
AC28	GPIO22[5,8]	I/O	NVDD
AD1	M1DQ31	I/O	GVDD1
AD2	M1DQ30	I/O	GVDD1
AD3	M1DQ27	I/O	GVDD1
AD4	M1ECC7	I/O	GVDD1
AD5	M1ECC6	I/O	GVDD1
AD6	M1ECC3	I/O	GVDD1
AD7	M1A9	O	GVDD1
AD8	M1A6	O	GVDD1
AD9	M1A3	O	GVDD1
AD10	M1A10	O	GVDD1
AD11	$\overline{\text{M1RAS}}$	O	GVDD1
AD12	M1A2	O	GVDD1
AD13	M1DQ38	I/O	GVDD1
AD14	$\overline{\text{M1DQS}}$5	I/O	GVDD1
AD15	M1DQS5	I/O	GVDD1
AD16	M1DQ33	I/O	GVDD1
AD17	M1DQ56	I/O	GVDD1
AD18	M1DQ57	I/O	GVDD1
AD19	$\overline{\text{M1DQS7}}$	I/O	GVDD1
AD20	M1DQS7	I/O	GVDD1
AD21	VSS	Ground	N/A
AD22	GE2_TX_CTL	O	NVDD
AD23	GPIO15/DDN0/$\overline{\text{IRQ15}}$/RC15[5,8]	I/O	NVDD
AD24	GPIO13/$\overline{\text{IRQ13}}$/RC13[5,8]	I/O	NVDD
AD25	GE_MDC	O	NVDD
AD26	GE_MDIO	I/O	NVDD
AD27	TDM2TCK/GE1_TD3[3]	I/O	NVDD
AD28	TDM2RCK/GE1_TD0[3]	I/O	NVDD
AE1	GVDD1	Power	N/A
AE2	VSS	Ground	N/A
AE3	M1DQ29	I/O	GVDD1
AE4	GVDD1	Power	N/A
AE5	VSS	Ground	N/A
AE6	M1ECC5	I/O	GVDD1
AE7	GVDD1	Power	N/A
AE8	VSS	Ground	N/A

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
AE9	M1A8	O	GVDD1
AE10	GVDD1	Power	N/A
AE11	VSS	Ground	N/A
AE12	M1A0	O	GVDD1
AE13	GVDD1	Power	N/A
AE14	VSS	Ground	N/A
AE15	M1DQ39	I/O	GVDD1
AE16	GVDD1	Power	N/A
AE17	VSS	Ground	N/A
AE18	M1DQ54	I/O	GVDD1
AE19	GVDD1	Power	N/A
AE20	VSS	Ground	N/A
AE21	GPIO29/UART_TXD[5,8]	I/O	NVDD
AE22	TDM1TCK/GE2_RX_CLK[3]	I	NVDD
AE23	TDM1RSN/GE2_RX_CTL[3]	I/O	NVDD
AE24	VSS	Ground	N/A
AE25	TDM3RCK/GE1_GTX_CLK[3]	I/O	NVDD
AE26	TDM3TSN/GE1_RX_CLK[3]	I/O	NVDD
AE27	TDM2RSN/GE1_TD2[3]	I/O	NVDD
AE28	TDM2RDT/GE1_TD1[3]	I/O	NVDD
AF1	M1DQ28	I/O	GVDD1
AF2	M1DM3	O	GVDD1
AF3	M1DQ26	I/O	GVDD1
AF4	M1ECC4	I/O	GVDD1
AF5	M1DM8	O	GVDD1
AF6	M1ECC2	I/O	GVDD1
AF7	M1CKE1	O	GVDD1
AF8	M1CK0	O	GVDD1
AF9	$\overline{\text{M1CK0}}$	O	GVDD1
AF10	M1BA1	O	GVDD1
AF11	M1A1	O	GVDD1
AF12	$\overline{\text{M1WE}}$	O	GVDD1
AF13	M1DQ37	I/O	GVDD1
AF14	M1DM4	O	GVDD1
AF15	M1DQ36	I/O	GVDD1
AF16	M1DQ32	I/O	GVDD1
AF17	M1DQ55	I/O	GVDD1
AF18	M1DM6	O	GVDD1
AF19	M1DQ53	I/O	GVDD1
AF20	M1DQ52	I/O	GVDD1
AF21	GPIO28/UART_RXD[5,8]	I/O	NVDD
AF22	TDM0RSN/GE2_TD2[3]	I/O	NVDD
AF23	TDM0TDT/GE2_TD3[3]	I/O	NVDD
AF24	NVDD	Power	N/A
AF25	TDM2TSN/GE1_TX_CTL[3]	I/O	NVDD
AF26	GE1_RX_CTL	I	NVDD

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
AF27	TDM2TDT/GE1_TX_CLK[3]	I/O	NVDD
AF28	TDM3RSN/GE1_RD1[3]	I/O	NVDD
AG1	M1DQ24	I/O	GVDD1
AG2	GVDD1	Power	N/A
AG3	M1DQ25	I/O	GVDD1
AG4	VSS	Ground	N/A
AG5	GVDD1	Power	N/A
AG6	M1ECC1	I/O	GVDD1
AG7	VSS	Ground	N/A
AG8	GVDD1	Power	N/A
AG9	M1A13	O	GVDD1
AG10	VSS	Ground	N/A
AG11	GVDD1	Power	N/A
AG12	$\overline{\text{M1CS1}}$	O	GVDD1
AG13	VSS	Ground	N/A
AG14	GVDD1	Power	N/A
AG15	M1DQ35	I/O	GVDD1
AG16	VSS	Ground	N/A
AG17	GVDD1	Power	N/A
AG18	M1DQ51	I/O	GVDD1
AG19	VSS	Ground	N/A
AG20	GVDD1	Power	N/A
AG21	NVDD	Power	N/A
AG22	TDM1TSN/GE2_TD1[3]	I/O	NVDD
AG23	TDM1RDT/GE2_TX_CLK[3]	I/O	NVDD
AG24	TDM0TCK/GE2_GTX_CLK[3]	I/O	NVDD
AG25	TDM1TDT/GE2_TD0[3]	I/O	NVDD
AG26	VSS	Ground	N/A
AG27	NVDD	Power	N/A
AG28	TDM3RDT/GE1_RD0[3]	I/O	NVDD
AH1	Reserved.	NC	—
AH2	$\overline{\text{M1DQS3}}$	I/O	GVDD1
AH3	M1DQS3	I/O	GVDD1
AH4	M1ECC0	I/O	GVDD1
AH5	$\overline{\text{M1DQS8}}$	I/O	GVDD1
AH6	M1DQS8	I/O	GVDD1
AH7	M1A5	O	GVDD1
AH8	$\overline{\text{M1CK1}}$	O	GVDD1
AH9	M1CK1	O	GVDD1
AH10	$\overline{\text{M1CS0}}$	O	GVDD1
AH11	M1BA0	O	GVDD1
AH12	$\overline{\text{M1CAS}}$	O	GVDD1
AH13	M1DQ34	I/O	GVDD1
AH14	$\overline{\text{M1DQS4}}$	I/O	GVDD1
AH15	M1DQS4	I/O	GVDD1
AH16	M1DQ50	I/O	GVDD1

Table 1. Signal List by Ball Number (continued)

Ball Number	Signal Name[1,2]	Pin Type[10]	Power Rail Name
AH17	$\overline{\text{M1DQS6}}$	I/O	GVDD1
AH18	M1DQS6	I/O	GVDD1
AH19	M1DQ48	I/O	GVDD1
AH20	M1DQ49	I/O	GVDD1
AH21	VSS	Ground	N/A
AH22	TDM0RCK/GE2_RD2[3]	I/O	NVDD
AH23	TDM0RDT/GE2_RD3[3]	I/O	NVDD
AH24	TDM0TSN/GE2_RD0[3]	I/O	NVDD
AH25	TDM1RCK/GE2_RD1[3]	I/O	NVDD
AH26	TDM3TDT/GE1_RD3[3]	I/O	NVDD
AH27	TDM3TCK/GE1_RD2[3]	I	NVDD
AH28	VSS	Ground	N/A

Notes:
1. Reserved signals should be disconnected for compatibility with future revisions of the device. Non-user signals are reserved for manufacturing and test purposes only. The assigned signal name is used to indicate whether the signal must be unconnected (Reserved), pulled down (VSS), or pulled up (VDD).
2. Signal function during power-on reset is determined by the RCW source type.
3. Selection of TDM versus RGMII functionality is determined by the RCW bit values.
4. Selection of RapidIO, SGMII, and PCI Express functionality is determined by the RCW bit values.
5. Selection of the GPIO function and other functions is done by GPIO register setup. For configuration details, see the *GPIO* chapter in the *MSC8252 Reference Manual*.
6. Open-drain signal.
7. Internal 20 KΩ pull-up resistor.
8. For signals with GPIO functionality, the open-drain and internal 20 KΩ pull-up resistor can be configured by GPIO register programming. See the *GPIO* chapter of the *MSC8252 Reference Manual* for configuration details.
9. Connect to power supply via external filter. See **Section 3.2**, *PLL Power Supply Design Considerations* for details.
10. Pin types are: Ground = all VSS connections; Power = all VDD connections; I = Input; O = Output; I/O = Input/Output; NC = not connected.

2 Electrical Characteristics

This document contains detailed information on power considerations, DC/AC electrical characteristics, and AC timing specifications. For additional information, see the *MSC8252 Reference Manual*.

2.1 Maximum Ratings

In calculating timing requirements, adding a maximum value of one specification to a minimum value of another specification does not yield a reasonable sum. A maximum specification is calculated using a worst case variation of process parameter values in one direction. The minimum specification is calculated using the worst case for the same parameters in the opposite direction. Therefore, a "maximum" value for a specification never occurs in the same device with a "minimum" value for another specification; adding a maximum to a minimum represents a condition that can never exist.

Table 2 describes the maximum electrical ratings for the MSC8252.

Table 2. Absolute Maximum Ratings

Rating	Power Rail Name	Symbol	Value	Unit
Core supply voltage • Cores 0–3	VDD	V_{DD}	–0.3 to 1.1	V
PLL supply voltage[3]		V_{DDPLL0} V_{DDPLL1} V_{DDPLL2}	–0.3 to 1.1 –0.3 to 1.1 –0.3 to 1.1	V V V
M3 memory supply voltage	M3VDD	V_{DDM3}	–0.3 to 1.1	V
DDR memory supply voltage • DDR2 mode • DDR3 mode	GVDD1, GVDD2	V_{DDDDR}	 –0.3 to 1.98 –0.3 to 1.65	 V V
DDR reference voltage	MVREF	MV_{REF}	–0.3 to 0.51 × V_{DDDDR}	V
Input DDR voltage		V_{INDDR}	–0.3 to V_{DDDDR} + 0.3	V
I/O voltage excluding DDR and RapidIO lines	NVDD, QVDD	V_{DDIO}	–0.3 to 2.625	V
Input I/O voltage		V_{INIO}	–0.3 to V_{DDIO} + 0.3	V
RapidIO pad voltage	SXPVDD1, SXPVDD2	V_{DDSXP}	–0.3 to 1.26	V
Rapid I/O core voltage	SXCVDD1, SXCVDD2	V_{DDSXC}	–0.3 to 1.21	V
Rapid I/O PLL voltage[3]		$V_{DDRIOPLL}$	–0.3 to 1.21	V
Input RapidIO I/O voltage		V_{INRIO}	–0.3 to V_{DDSXC} + 0.3	V
Operating temperature		T_J	–40 to 105	°C
Storage temperature range		T_{STG}	–55 to +150	°C

Notes:
1. Functional operating conditions are given in Table 3.
2. Absolute maximum ratings are stress ratings only, and functional operation at the maximum is not guaranteed. Stress beyond the listed limits may affect device reliability or cause permanent damage.
3. PLL supply voltage is specified at input of the filter and not at pin of the MSC8252 (see Figure 37 and Figure 38)

2.2 Recommended Operating Conditions

Table 3 lists recommended operating conditions. Proper device operation outside of these conditions is not guaranteed.

Table 3. Recommended Operating Conditions

Rating	Symbol	Min	Nominal	Max	Unit
Core supply voltage	V_{DD}	0.97	1.0	1.05	V
M3 memory supply voltage	V_{DDM3}	0.97	1.0	1.05	V
DDR memory supply voltage • DDR2 mode • DDR3 mode DDR reference voltage	V_{DDDDR} MV_{REF}	 1.7 1.425 $0.49 \times V_{DDDDR}$	 1.8 1.5 $0.5 \times V_{DDDDR}$	 1.9 1.575 $0.51 \times V_{DDDDR}$	 V V V
I/O voltage excluding DDR and RapidIO lines	V_{DDIO}	2.375	2.5	2.625	V
Rapid I/O pad voltage	V_{DDSXP}	0.97	1.0	1.05	V
Rapid I/O core voltage	V_{DDSXC}	0.97	1.0	1.05	V
Operating temperature range: • Standard • Higher • Extended	 T_J T_J T_A T_J	 0 0 –40 —		 90 105 — 105	 °C °C °C
Typical power: 1 GHz at 1.0 V[1]	P	—	3.54	—	W

Notes: 1. The typical power values are derived for a device running under the following conditions.
- Two cores running at 1 GHz, Core voltage at 1V, 75% utilization (50% control/50% DSP).
- A single 64 bit DDR3 running at 800 MHz, 50% utilization (50% reads/50% writes).
- M3 Memory 50% utilized, PCI Express controller disabled, TDM enabled 20% loading, Serial RapidIO controller disabled, 1 RGMII at 1 Gbps 50% loading.
- A junction temperature of 60°C.

2.3 Thermal Characteristics

Table 4 describes thermal characteristics of the MSC8252 for the FC-PBGA packages.

Table 4. Thermal Characteristics for the MSC8252

Characteristic	Symbol	FC-PBGA 29 × 29 mm²		Unit
		Natural Convection	200 ft/min (1 m/s) airflow	
Junction-to-ambient[1, 2]	$R_{\theta JA}$	18	12	°C/W
Junction-to-ambient, four-layer board[1, 2]	$R_{\theta JA}$	13	9	°C/W
Junction-to-board (bottom)[3]	$R_{\theta JB}$	5		°C/W
Junction-to-case[4]	$R_{\theta JC}$	0.6		°C/W

Notes:
1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.
2. Junction-to-ambient thermal resistance determined per JEDEC JESD51-3 and JESDC51-6. Thermal test board meets JEDEC specification for the specified package.
3. Junction-to-board thermal resistance determined per JEDEC JESD 51-8. Thermal test board meets JEDEC specification for the specified package.
4. Junction-to-case at the top of the package determined using MIL- STD-883 Method 1012.1. The cold plate temperature is used for the case temperature. Reported value includes the thermal resistance of the interface layer

2.4 CLKIN Requirements

Table 5 summarizes the required characteristics for the CLKIN signal.

Table 5. CLKIN Requirements

Parameter/Condition[1]	Symbol	Min	Typ	Max	Unit	Notes
CLKIN duty cycle	—	40	—	60	%	2
CLKIN slew rate	—	1	—	4	V/ns	3
CLKIN peak period jitter	—	—	—	±150	ps	—
CLKIN jitter phase noise at –56 dBc	—	—	—	500	KHz	4
AC input swing limits	ΔV_{AC}	1.5	—	—	V	—
Input capacitance	C_{IN}	—	—	15	pf	—

Notes:
1. For clock frequencies, see the *Clock* chapter in the *MSC8252 Reference Manual.*
2. Measured at the rising edge and/or the falling edge at $V_{DDIO}/2$.
3. Slew rate as measured from ±20% to 80% of voltage swing at clock input.
4. Phase noise is calculated as FFT of TIE jitter.

2.5 DC Electrical Characteristics

This section describes the DC electrical characteristics for the MSC8252.

2.5.1 DDR SDRAM DC Electrical Characteristics

This section describes the DC electrical specifications for the DDR SDRAM interface of the MSC8252.

Note: DDR2 SDRAM uses V_{DDDDR}(typ) = 1.8 V and DDR3 SDRAM uses V_{DDDDR}(typ) = 1.5 V.

2.5.1.1 DDR2 (1.8 V) SDRAM DC Electrical Characteristics

Table 6 provides the recommended operating conditions for the DDR SDRAM controller when interfacing to DDR2 SDRAM.

Note: At recommended operating conditions (see Table 3) with V_{DDDDR} = 1.8 V.

Table 6. DDR2 SDRAM Interface DC Electrical Characteristics

Parameter/Condition	Symbol	Min	Max	Unit	Notes
I/O reference voltage	MV_{REF}	0.49 × V_{DDDDR}	0.51 × V_{DDDDR}	V	2, 3, 4
Input high voltage	V_{IH}	MV_{REF} + 0.125	V_{DDDDR} + 0.3	V	5
Input low voltage	V_{IL}	–0.3	MV_{REF} – 0.125	V	5
I/O leakage current	I_{OZ}	–50	50	µA	6
Output high current (V_{OUT} (VOH) = 1.37 V)	I_{OH}	–13.4	—	mA	7
Output low current (V_{OUT} (VOL) = 0.33 V)	I_{OL}	13.4	—	mA	7

Notes:
1. V_{DDDDR} is expected to be within 50 mV of the DRAM V_{DD} supply voltage at all times. The DRAM and memory controller can use the same or different sources.
2. MV_{REF} is expected to be equal to 0.5 × V_{DDDDR}, and to track V_{DDDDR} DC variations as measured at the receiver. Peak-to-peak noise on MV_{REF} may not exceed ±2% of the DC value.
3. V_{TT} is not applied directly to the device. It is the supply to which far end signal termination is made and is expected to be equal to MV_{REF} with a minimum value of MV_{REF} – 0.4 and a maximum value of MV_{REF} + 0.04 V. V_{TT} should track variations in the DC-level of MV_{REF}.
4. The voltage regulator for MV_{REF} must be able to supply up to 300 µA.
5. Input capacitance load for DQ, DQS, and DQS signals are available in the IBIS models.
6. Output leakage is measured with all outputs are disabled, 0 V ≤ V_{OUT} ≤ V_{DDDDR}.
7. Refer to the IBIS model for the complete output IV curve characteristics.